

Introduction to the 3D-HiPMAS project

*Pilot Factory for 3D High
Precision MID Assemblies*

Logo

A new high precision technology
for new market opportunities



General project data

Title: Pilot Factory for 3D High Precision MID Assemblies (3D-HiPMAS)

Call: FoF.NMP.2012-5

High precision production technologies for high quality 3D micro-parts

Period: 01/10/2012 – 30/09/2015 (36 month)

Budget: 5,350,276,20€

Grant: 3,499,600,00€

Partners: 12

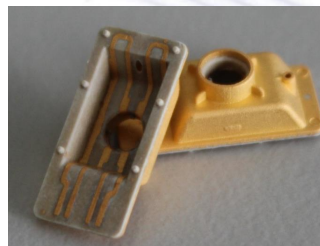
Coordinator: HSG-IMAT

Project partners



Content :

- State of the art
- Objectives
- Building Blocks – Beyond state of the art
- Resources - Budget
- Impacts
- Dissemination

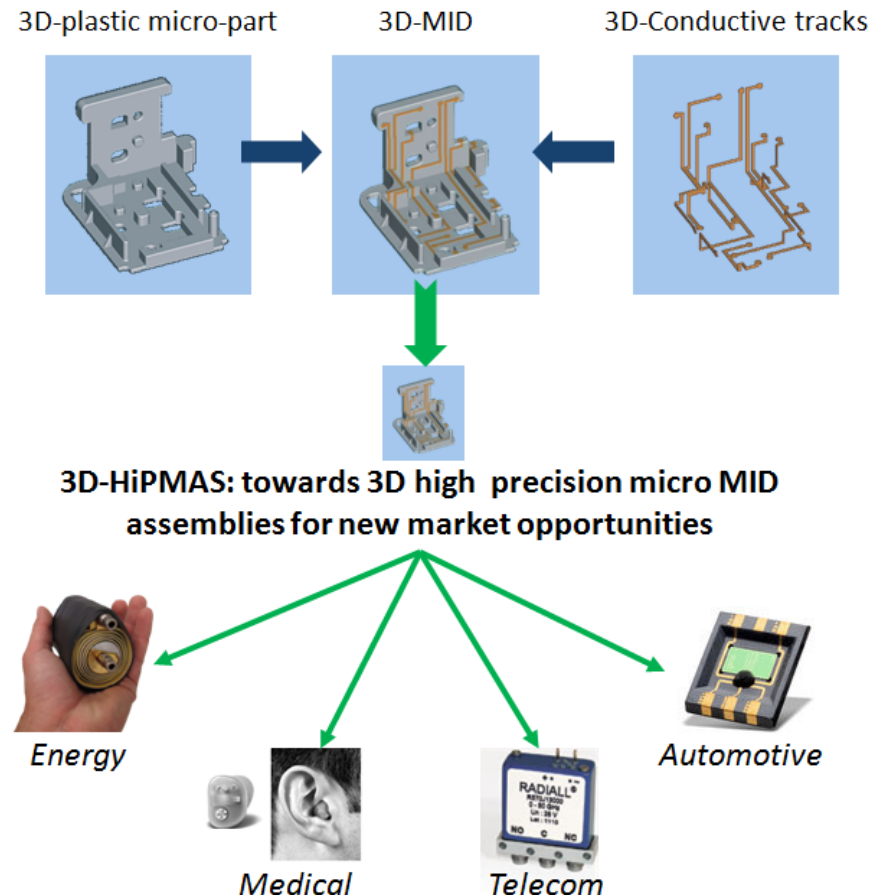


Subject : MID based 3D high quality, high precision 3D micro-parts

Process Flow:

- 3D plastics micro-parts
- conductive tracks
- components assembly
- online monitoring / quality inspection

→ **Huge Potential for new Products and Production in Europe!**

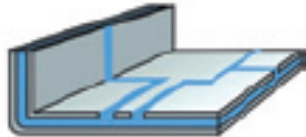


SoA : 2-shot MID Technology

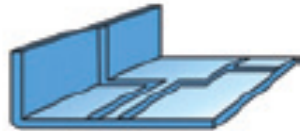
Injection mould first shot



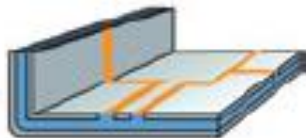
Injection mould second shot



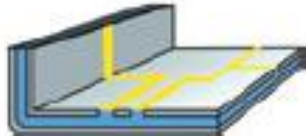
Surface activation



Full-build electroless copper



Surface finish



Process Flow of 2-shot MID



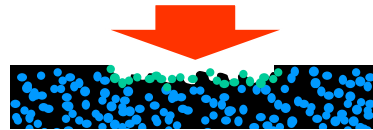
Pressure Sensor Assembly:

- 2-shot MID saves ~50% of space
- 2-shot MID saves ~ 30% of cost

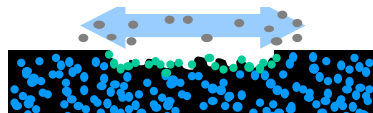
SoA : Laser Direct Structuring MID Technology (LDS)



Injection moulding



IR-Laser structuring



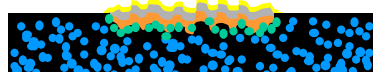
Cleaning



Electroless Cu



Electroless Ni



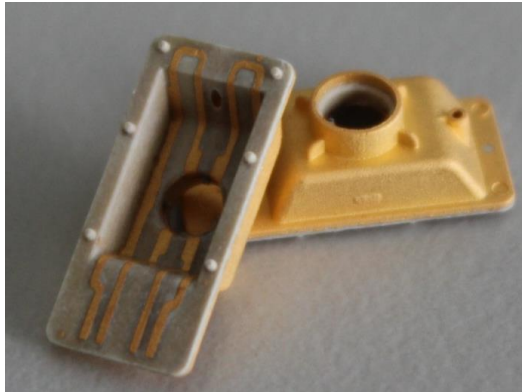
Immersion Au

Process Flow of LDS MID

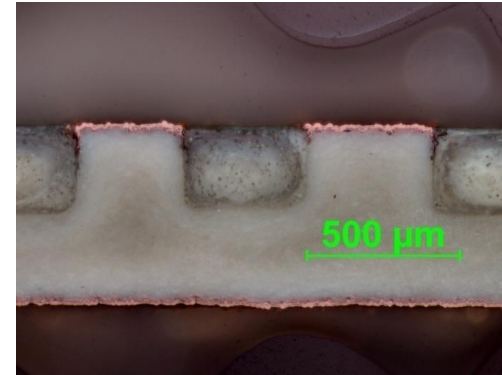


Switch for Motor Cycle Handlebar

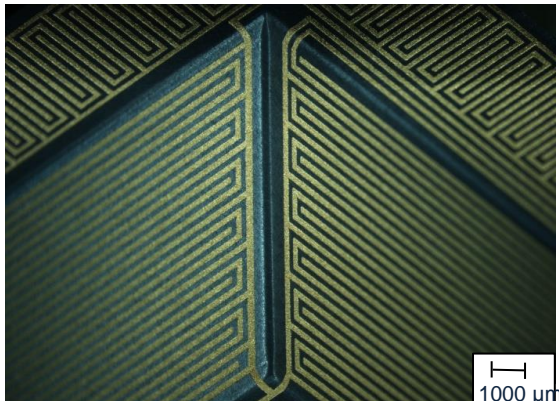
SoA : Electroless Metal Deposition for 2-shot and LDS MIDs



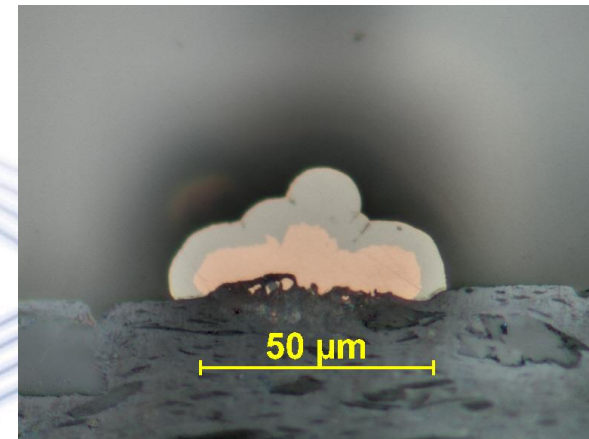
2-Shot MID at 600 μm pitch



Lateral metal over grow in 2-Shot MID

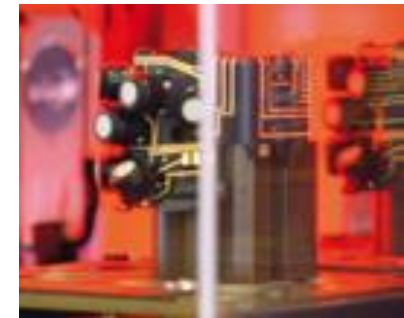


LDS MID at 300 μm pitch



Lateral metal over grow in LDS MID

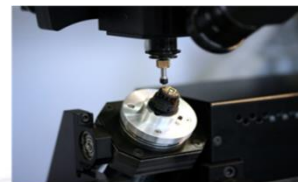
SoA : Assembling of Electronic Devices of 3D-MIDs



Motor cycle handlebar switch



Light sensor



3D chip assembly with tilt of MID



SMD assembly



Fabrication line

Light sensor for car environmental control

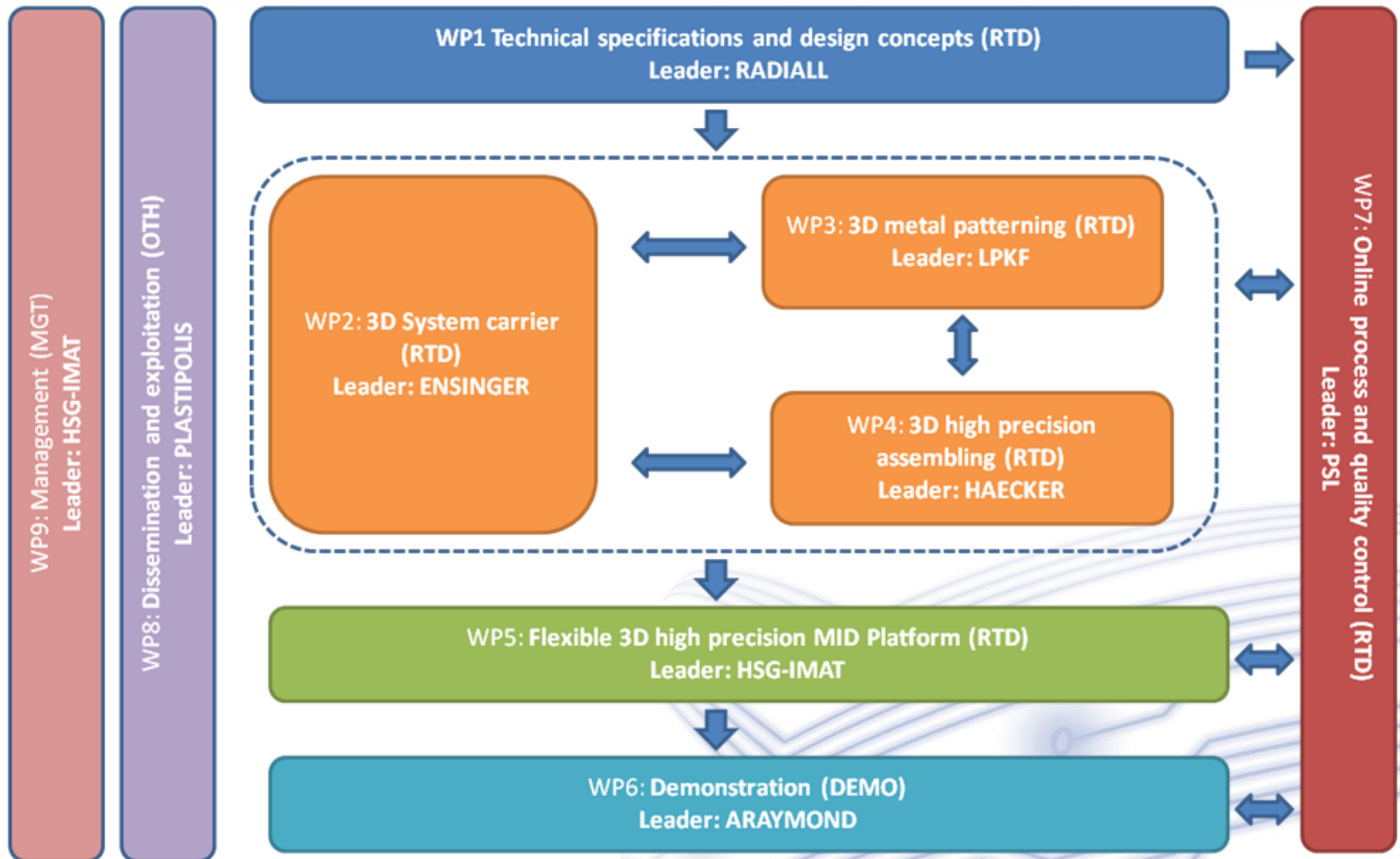


State of the art bottlenecks to be addressed :

- **Plastics Material**
- **2-Shot moulding process**
- **Laser technology**
- **Electroless metal deposition**
- **Assembly of electronic components on 3D bodies**
- **In-line monitoring of 3D micro-parts**
- **Experience of industries along the MID assemblies process chain**
- **Production cost**
- **Material consumption and environmental protection**

Overall project objectives :

- **3D high precision 2-shot plastics micro-parts** with size reduction for conductive tracks from SoA 300µm to 150µm
- **3D high definition conductive tracks** by new generation of Laser Direct Structuring and plating technologies reduced from SoA 300 µm pitch in 3D (150 µm in 2D) to 150 µm pitch in 3D (75 µm in 2D)
- **3D precision electronic components assembly** with novel overall capability of positioning and alignment accuracy below 10µm compared to SoA 20µm
- **3D reliable and robust online monitoring and quality inspection system**, including quality management, and novel in-line 3D X-Ray tomography.
- **Integrating these 4 technologies to launch the future EU pilot factory** to save more than 50% of today's production costs
- **Assessment of the pilot factory through 4 advanced products** in the energy, medical, communication and transport applications.



Beyond SoA : 3D system carrier

New plastic materials with cost kept at present level:

- higher performance and precision 3D system carriers
- thermal expansion reduced by 30 %

New additives at size below 1 μm :

- enable LDS activation and plating phases
- good stability and perfect cohesion with the polymer matrix

Enhanced precision 2-shot molded 3D micro-parts:

- reduced wall thickness, line width and tolerances
- using rapid heat&cool, vacuum and compression moulding

Improved processing performance:

- reduction of material consumption by wall thickness and part size of 20%
- reduction of mould set up phase and time-to-market by 10 %
- improved precision by 50%

Beyond SoA : 3D metal patterning

Improving laser machinery:

- Reducing laser spot size from 60 μm to below 25 μm
- Improving positioning accuracy from 10-20 μm (3 sigma) to 5-7 μm
- Enhancing Scanning velocity for same throughput (mm^2/s)
- Reducing machining cost by 50%
- Image processing for online process control

Improved metal plating for LDS and 2-shot (roughness, adhesion):

- Reduced size of metal lines for LDS (100%) and 2-Shot MID
- Cleaning processes for 50% less CO_2 or chemicals consumption
- Replace Ni-P/Au by Ag for less chemicals / metals consumption
- More pieces per batch due to smaller device size (30 - 50 %)

Reduced cost:

- laser machining ~50 %
- metal deposition ~35 – 60 %

Beyond SoA : 3D high precision assembling

Improving precision and 3D capability of assembling machinery:

- Develop 3-D manipulation to work on a globe and around it to transfer parts, move parts, rotate parts and more
- Increase z-stroke from 45 mm to 150 mm for more complex MID
- Reduce cycle time at increased z-stroke while maintaining precision and accuracy
- Develop new sorting process for loose material parts to work piece carriers

Improving joining processes for new fine pitch MID:

- Establish new laser soldering capabilities for 3-D connections
- Develop joining processes for “bare dies”
- Develop joining processes for SMD
- Develop joining processes for micromechanical/micro optical components
- Develop automatic loading options for complex MID structures
- Implement image processing for real time control of assembly and dispensing results and reevaluate automatic error compensation.

Beyond SoA : Advanced product and process control

Advance software platform for engineers for 3D- μ -MIDs products:

- MID/3D-MID domain-specific language specification
- Software environments dedicated to 3D-MID/MID process engineering

Relevant online process and product quality inspection strategy for 3D- μ -MIDs products

In-line non destructive 3 dimensional metrology tool:

- enabling feedback on production process / quality achieved
- innovative concept of X-Ray tomograph
- Radio Synthetic Control (RSC) for non destructive 3 D analysis of complex volumes analysis of material content using real time X-ray imaging acquisition
- Reduced overheads in reconstructing 3D data sets by 80-90%

Demonstrator 1 : 3D micro fuel cell

Beyond SoA:

Integration of a.m.a.p of control and safety parts into MID / package

- control electronics
- sensors
- piezoelectric actuators for valves / circuit-breakers

Miniaturization:

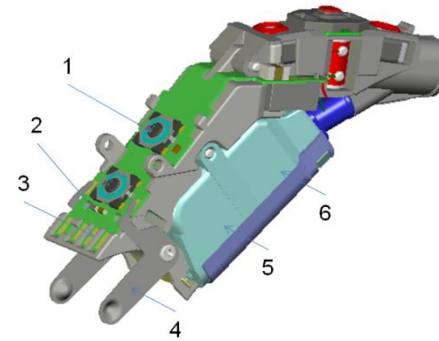
- lower number of parts
- smaller size
- lower power consumption
- reduced cost by 60% for control and safety part



Demonstrator 2 : 3D micro hearing aids



Phonak BTE type hearing aid



Beyond SoA:

- Integration of antenna structures
- 3D integration of electronic components
- Integration of contact elements
- Evaluation of hard/soft material combination compatible to 3D MID process

Demonstrator 3 : 3D micro switches

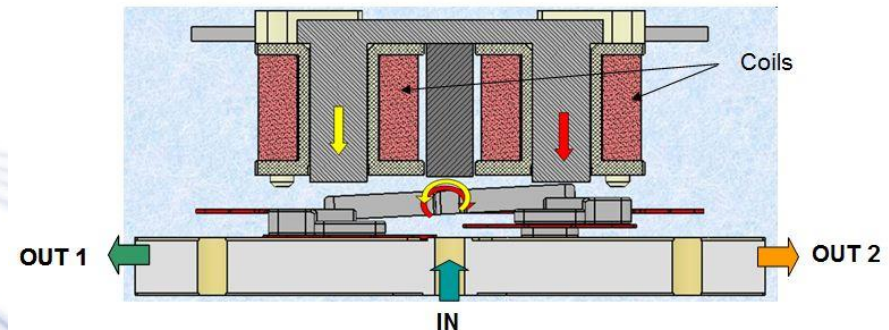
Beyond SoA:

Cost reduction for new market opportunity (~30%)

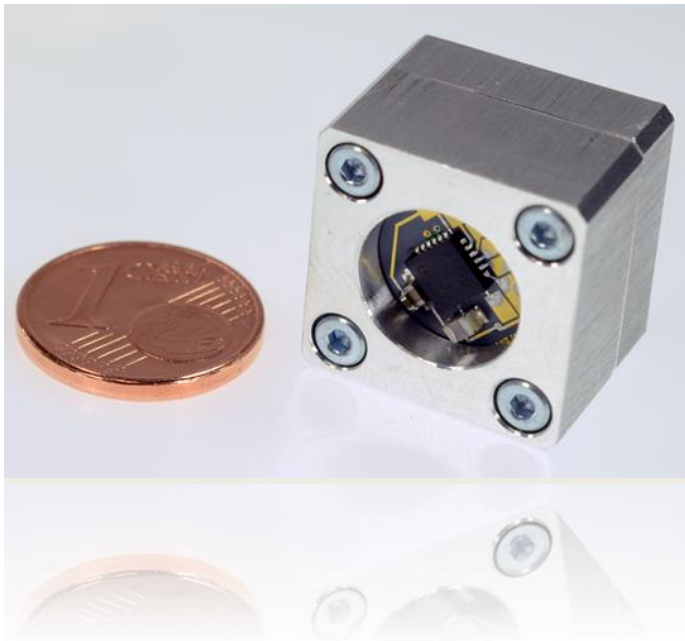
- Improved assembly process
- Less higher precision of parts (15 to 8)
- Chance of automation
- improved reliability

Improved RF performances

- new MID based design
- New RF line design for improved the frequency level (8 to 12 GHz)
- Improved harsh environment capability



Demonstrator 4 : MID based pressure sensor



Thanks to MIDs, this very robust pressure sensor based on a membrane / capacitive principle with an integrated temperature sensor display a smaller package volume and will provide a cost-effective solution for many sensor applications.

Assessment of pilot line performance during demonstration :

- Reduction of **plastics materials** input
- Reduction of **energy consumption** in materials compounding, injection moulding, metal deposition and laser machining
- Reduction of **CO₂ consumption** and/or chemicals in cleaning
- Reduction of consumption of process **chemicals** and **metals** in electroless plating (Au will be replaced to 100%)
- Improvement of **precision**
- Improvement of **yield**

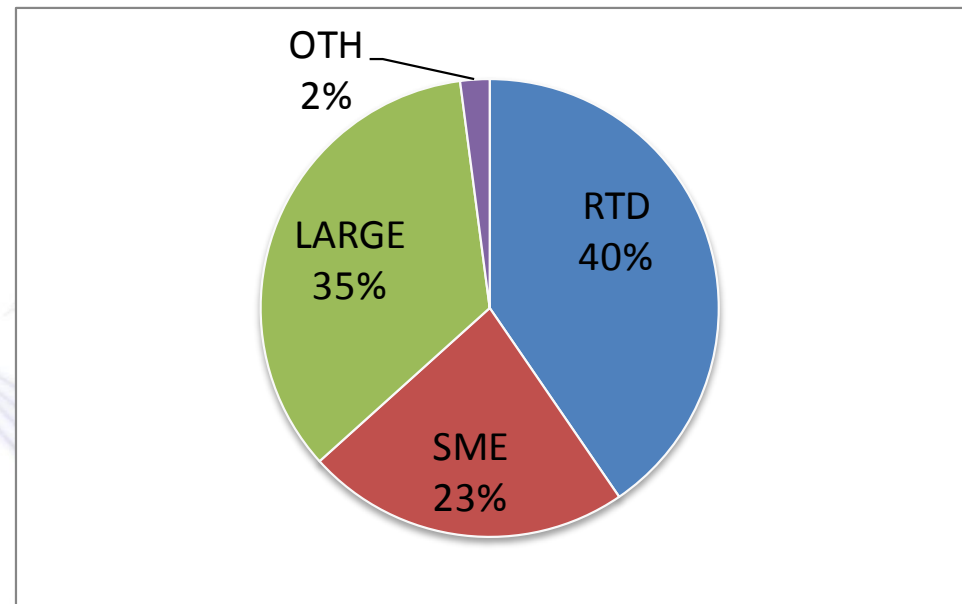
Planned resources

Participant Nr	Organization short name	Organization country	RTD	DEMO	MGT	OTH	Total	Requested EU contribution
1	HSG-IMAT	DE	599.504	131.016	171.488	35.126	937.134	721.750
2	LPKF	DE	507.576	60.576	0	16.032	584.184	300.108
3	PSL	UK	396.349	184.794	1.500	20.283	602.926	411.441
4	HAECKER	DE	372.307	81.692	0	29.419	483.418	349.495
5	RADIALL	FR	171.618	249.034	0	18.577	439.229	228.903
6	PRAGMA	FR	46.930	120.192	0	14.178	181.300	109.471
7	PHONAK	CH	65.370	238.484	0	11.706	315.560	163.633
8	PEP	FR	506.000	142.600	1.500	32.800	682.900	485.100
9	CEA	FR	385.198	45.742	0	13.297	444.237	325.066
10	PLASTIPOLIS	FR	0	0	0	113.076	113.076	113.076
11	ENSINGER	DE	173.155	30.014	0	8.616	211.785	110.200
12	RAYCE	FR	79.978	266.362	0	8.187	354.527	181.357
	TOTAL		3.303.985	1.550.506	174.488	321.297	5.350.276	3.499.600

Budget share

	Budget [€]	Share [%]
Personal	4094032	76,52
Consumable	1205444	22,53
Equipment		
Travel		
Other	50800	0,95
Subcontracting		

Grant/Total Budget : 64%
 Management Budget: 5%



3D-HiPMAS impacts :

Provide the industry with a pilot factory able to offer customised solutions in terms of technical and economical performances

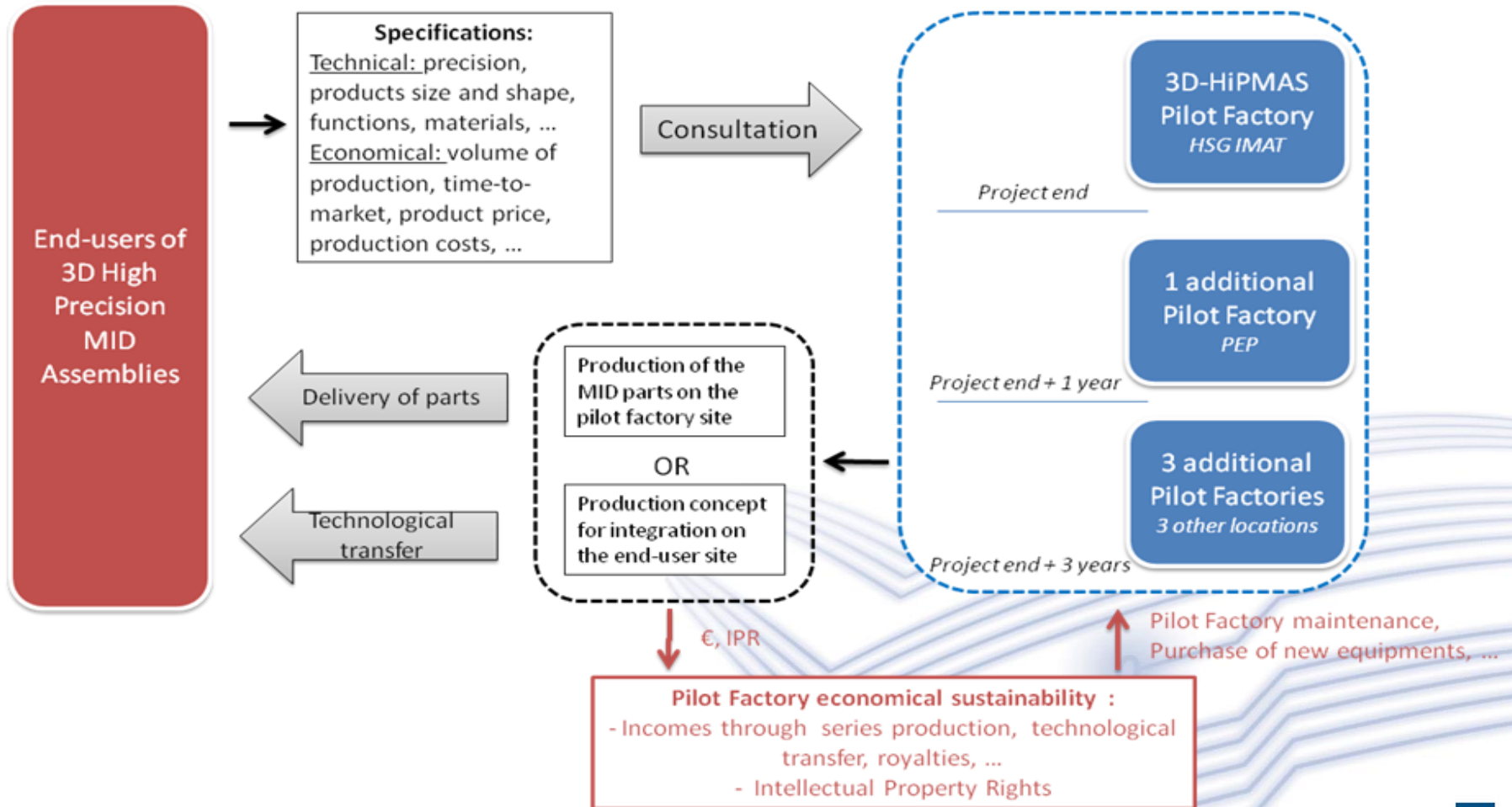
▪Supply chain:

- Consultation of companies on the Pilot Factory (precision, products size, shape, functions, materials, volume of production, time-to-market, product price, production costs ...).
- Studies on efficient production for manufacturing of MID components
- Set up of fabrication lines within Europe

▪Open the way to new future products not possible to be realized using SoA technology:

- Health care
- Mobility
- Communication
- Energy

Dissemination of the 3D-HiPMAS pilot line :



Dissemination of the results and IP :

- **Communication:**

Website, brochure, press releases, conferences journals

- **Pilotline:**

Consulting, training courses, pilot production, production services...

- **Satellite Group:**

Direct contact to interested industries

- **Workshop with contest:**

Case studies, pilot production

THANK YOU FOR
YOUR ATTENTION

Logo

A new high precision technology
for new market opportunities

